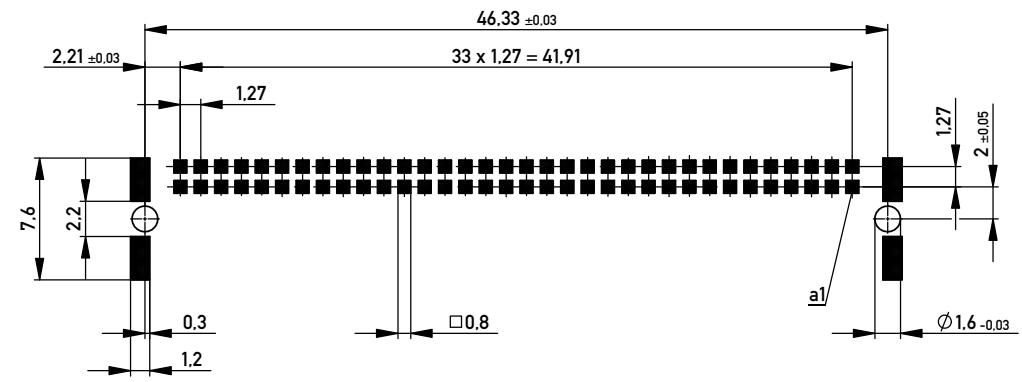


Leiterplatten-Layout Vorschlag für SMT  
PCB-Layout Proposal for SMT



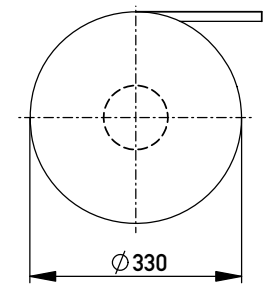
Anforderungsstufe 1  
Performance Level 1

Kontaktbereich vergoldet  
Mating Area gold plating

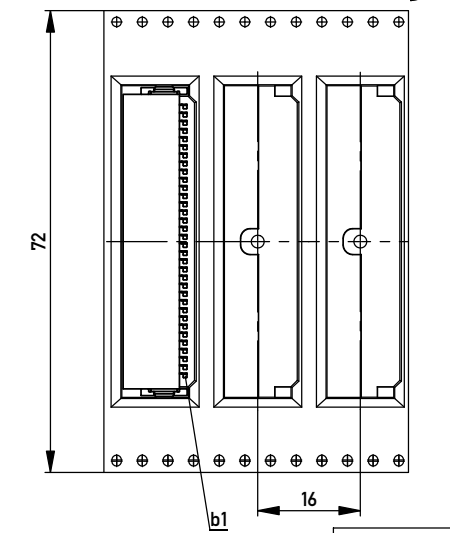
Anschlussbereich verzinkt 4-6 µm  
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm  
Coplanarity Area of Termination ≤ 0,1 mm

Verpackt im Gurt nach DIN IEC 60286-3  
Tape on Reel Packaging according to DIN IEC 60286-3  
Verpackungseinheit: 560 Stück  
Packaging unit: 560 pcs



Abspulrichtung - Reel off Direction



BA7-03 - Standard Bauhöhe  
type7-03 - Standard Assembly Height

Information:  All rights reserved. Only for Information. To ensure that this is the latest version of this drawing, please contact one of the ERNI companies before using.	Tolerances	 All Dimensions in mm	Scale	3:1
	Subject to modification without prior notice. Drawing will not be updated.		Designation	<b>Messertl. SMC-B 68-SMD-BA7-03</b> <b>Male SMC-B 68-SMD-type7-03</b>
e Index	25.06.2015 Date	 www.ERNI.com	154766	I A3
			Class	SMCB

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